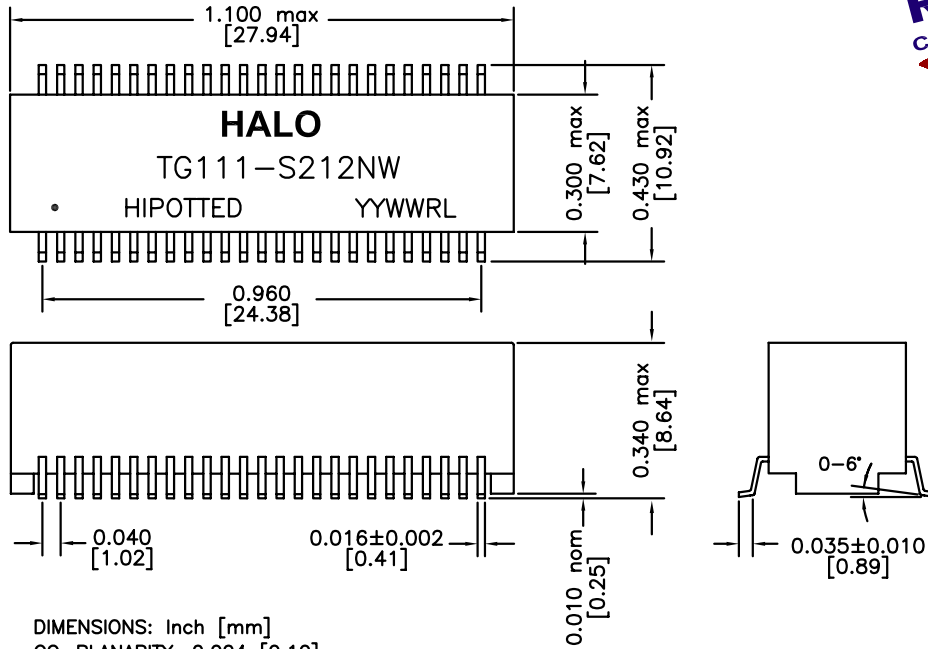


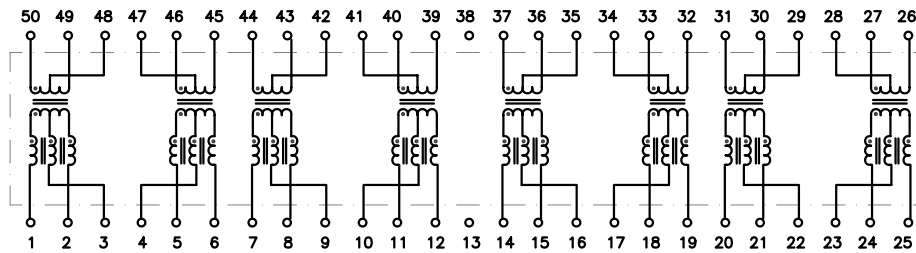


PART NO. : TG111-S212NWRL

50PIN 0.040" LEAD PITCH SMT PACKAGE
 DESIGNED FOR DUAL-PORT GIGABIT, IEEE802.3ab OR
 FOUR-PORT FAST ETHERNET, IEEE802.3u APPLICATIONS
 COMPLIANT WITH IEEE802.3af REQUIREMENTS WITH
 350mA CURRENT CARRYING CAPACITY FOR PoE
 RoHS COMPLIANT
 COMPATIBLE TO LEAD-FREE SOLDERING PROCESS
 CONDITION PER IPC/JEDEC J-STD-020C
 UL/EN60950 AND DEMKO RECOGNIZED
 OPERATING TEMPERATURE 0/70°C



DIMENSIONS: Inch [mm]
 CO-PLANARITY: 0.004 [0.10]
 TOLERANCES: ±0.005 INCH IF NOT SPECIFIED



ELECTRICAL SPECIFICATIONS @ 25° C

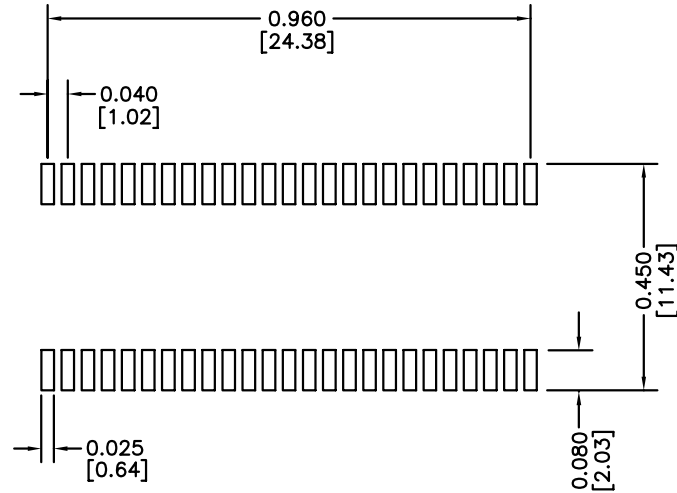
URNS RATIO	1CT:1CT±2%
OCL (100KHz,0.1Vrms,8mADC)	350µH min
INSERTION LOSS 1-100MHz	-1.1dB max
RETURN LOSS 1-40MHz	-18dB min
60MHz	-14dB min
80MHz	-12dB min
100MHz	-10dB min
CMR 1-100MHz	-40dB typ
CROSSTALK 1-30MHz	-50dB typ
60MHz	-45dB typ
100MHz	-40dB typ
ISOLATION	1,500Vrms



HALO/PBL

CALIFORNIA, USA
 KOWLOON, HONG KONG
 SINGAPORE

TITLE	ISOLATION MODULE		SIGNATURES	DATE	REV.	DESC.	DATE
	FOR	FAST/GIGABIT ETHERNET	DRAWN PETER LU	11/8/05	A	FIRST ISSUE	11/8/05
	PART NO.	TG111-S212NWRL	CHECKED LEI KEONG	3/20/08	B	PROD. RELEASE	12/21/06
	SCALE	NONE	APPROVED PETER LU	3/20/08	C	REV. TOE LENGTH TOL.	3/20/08
	PAGE	1 OF 2	FILE	S212NWRL.DWG			



RECOMMENDED SOLDER PAD DIMENSIONS
 DIMENSIONS: Inch [mm]

HALO/PBL CALIFORNIA, USA KOWLOON, HONG KONG SINGAPORE	TITLE	ISOLATION MODULE	SIGNATURES		DATE	REV.	DESC.	DATE
	FOR	FAST/GIGABIT ETHERNET	DRAWN	PETER LU	11/8/05	A	FIRST ISSUE	11/8/05
	PART NO.	TG111-S212NWRL	CHECKED	LEI KEONG	3/20/08	B	PROD. RELEASE	12/21/06
	SCALE	NONE	APPROVED	PETER LU	3/20/08	C	REV. TOE LENGTH TOL.	3/20/08
		PAGE	2 OF 2	FILE	S212NWRL.DWG			